**삼성전자 CE/IM부문 현장실습 참가 신청서**

작성일 : 2021. 00. 00

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| **인**  **적**  **사**  **항** | **성명** |  | **영문성명** |  |
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| **대학교** | YYYY.MM | YYYY.MM |  | ※ 주전공, 복수전공 등  이수예정 전공 모두 작성 |  | 0.0/0.0 |

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| **자격**  **사**  **항** | **특수자격및면허** | **등급** |  | **어**  **학**  **사**  **항** | **영어** | 점(응시명) |  | **특**  **기**  **사**  **항** | **병역구분** | 필/미필/면제 |
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| **지원 동기(500자 이상)** |  |
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| **장점과 단점(500자 이상)** |  |
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